

### Features

- Solid-state silicon-avalanche technology
- 300 Watts Peak Pulse Power per Line ( $t_p=8/20\mu s$ )
- Low operating and clamping voltage
- Up to four I/O Lines of Protection
- Low Leakage current
- Low operating voltage:5V

### IEC COMPATIBILITY (EN61000-4)

- IEC 61000-4-2 (ESD)  $\pm 30kV$  (air),  $\pm 30kV$  (contact)
- IEC 61000-4-4 (EFT) 40A (5/50ns)
- IEC 61000-4-5 (Lightning) 12A (8/20 $\mu s$ )

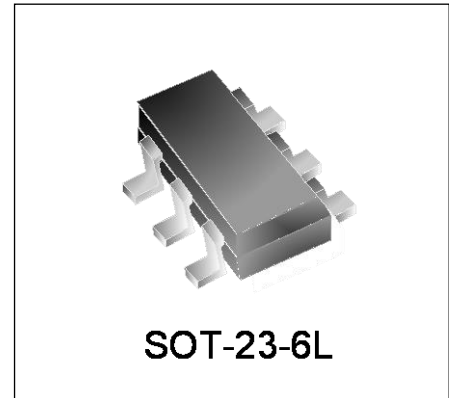
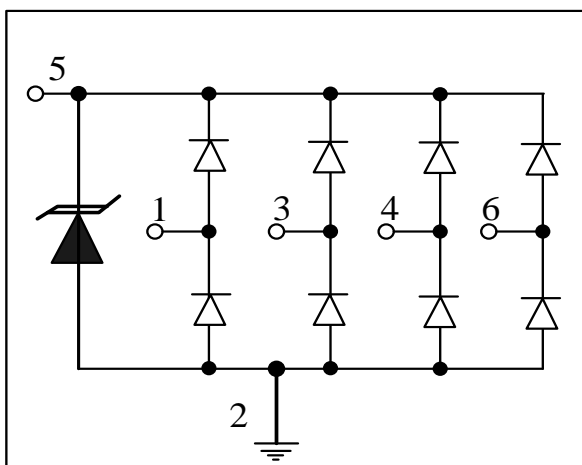
### Mechanical Characteristics

- SOT-23-6L package
- Marking: Marking Code
- Packaging: Tape and Reel
- RoHS Compliant & HF
- Device meets MSL1 requirement
- AEC-Q101 Qualified

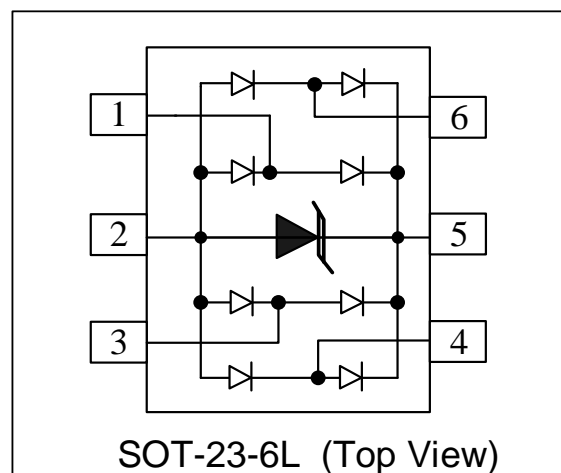
### Applications

- Video/Graphics Card
- Handheld & Portable Electronics
- PC/Notebook USB2.0/IEEE1394 ports
- 10/100/1000 Ethernet
- DVI interfaces
- Wireless data (WAN/LAN) systems

### Circuit Diagram



### Schematic & PIN Configuration

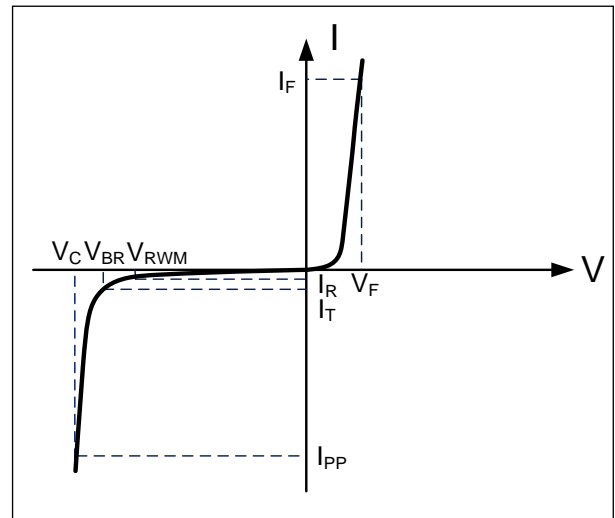


**Absolute Maximum Rating**

Rating	Symbol	Value	Units
Peak Pulse Power ( $t_p = 8/20\mu s$ )	$P_{PP}$	300	Watts
Peak Pulse Current ( $t_p = 8/20\mu s$ )	$I_{PP}$	12	A
Operating Temperature	$T_J$	-55 to + 150	°C
Storage Temperature	$T_{STG}$	-55 to +150	°C

**Electrical Parameters**

Symbol	Parameter
$I_{PP}$	Reverse Peak Pulse Current
$V_C$	Clamping Voltage @ $I_{PP}$
$V_{RWM}$	Reverse Stand-Off Voltage
$I_R$	Reverse Leakage Current @ $V_{RWM}$
$V_{BR}$	Reverse Breakdown Voltage @ $I_T$
$I_T$	Test Current
$I_F$	Forward Current
$V_F$	Forward Voltage @ $I_F$



**Electrical Characteristics (T=25°C unless otherwise noted)**

WS05-4R-AT						
Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	$V_{RWM}$				5	V
Reverse Breakdown Voltage	$V_{BR}$	$I_T=1mA$	6			V
Reverse Leakage Current	$I_R$	$V_{RWM}=5V$			500	nA
Clamping Voltage	$V_C$	$I_{PP}=12A, t_p=8/20\mu s$ Any I/O pin to GND		20	25	V
Dynamic Resistance <sup>1,2</sup>	$R_{DYN}$	TLP=0.2/100ns		0.36		$\Omega$
ESD Clamping Voltage <sup>1</sup>	$V_C$	$I_{PP} = 4A,$ $t_p = 0.2/100ns$ (TLP)		9.7		V
ESD Clamping Voltage <sup>1</sup>	$V_C$	$I_{PP} = 16A,$ $t_p = 0.2/100ns$ (TLP)		14		V
Junction Capacitance	$C_j$	$V_R = 0V, f = 1MHz$ I/O pin to GND		1.5	2	pF
		$V_R = 0V, f = 1MHz$ Between I/O pins		0.75	1	pF

Notes : 1. TLP Setting :  $t_p=100ns, t_r=0.2ns, I_{TLP}$  and  $V_{TLP}$  sample window: $t_1=70ns$  to  $t_2=90ns$ .  
 2. Dynamic resistance calculated from  $I_{PP}=4A$  to  $I_{PP}=16A$  using "Best Fit".

Typical Characteristics

Figure 1: Peak Pulse Power vs. Pulse Time

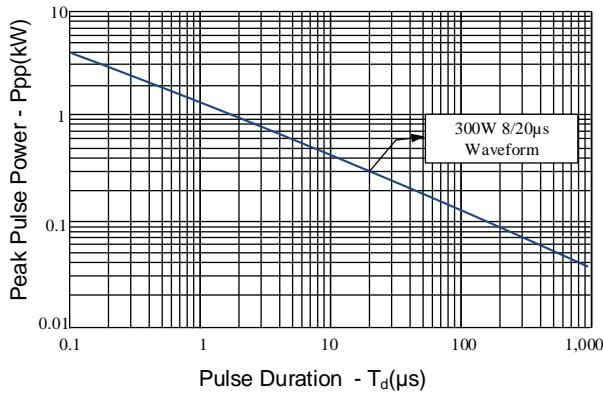


Figure 2: Power Derating Curve

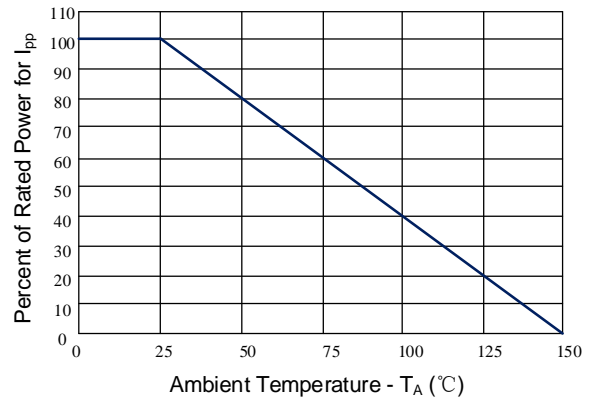


Figure 3: Clamping Voltage vs. Peak Pulse Current

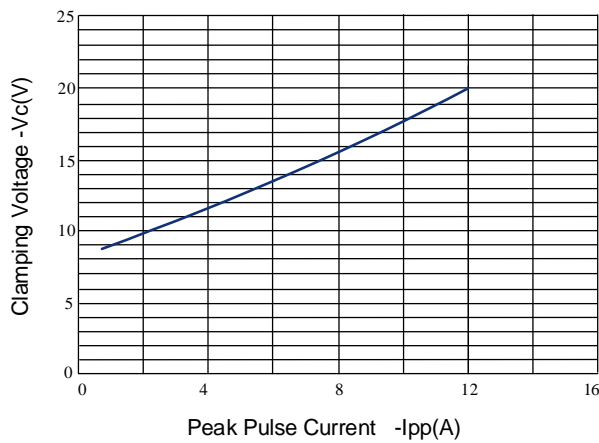


Figure 4: Normalized Junction Capacitance vs. Reverse Voltage (I/O-GND)

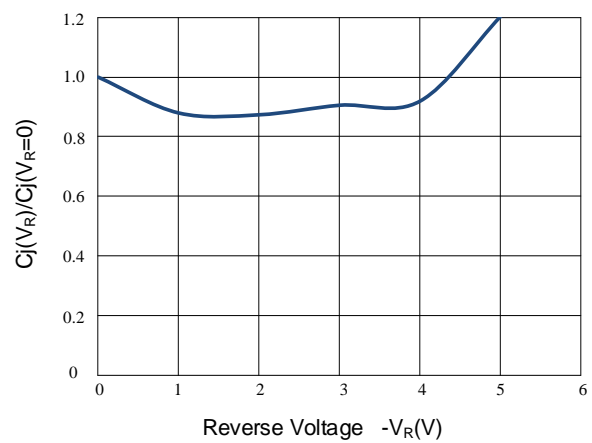


Figure 5: 8/20μs Pulse Waveform

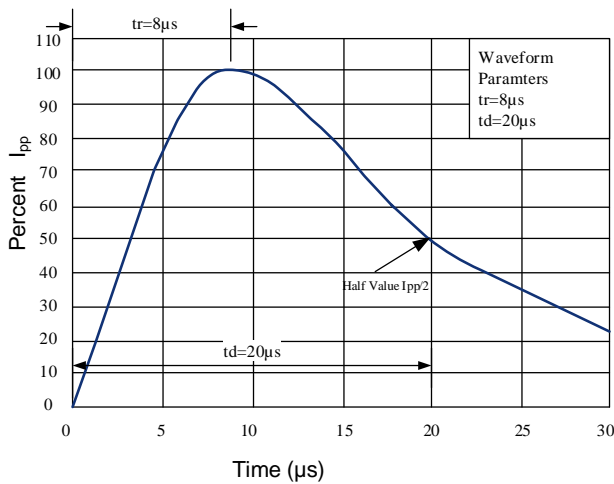
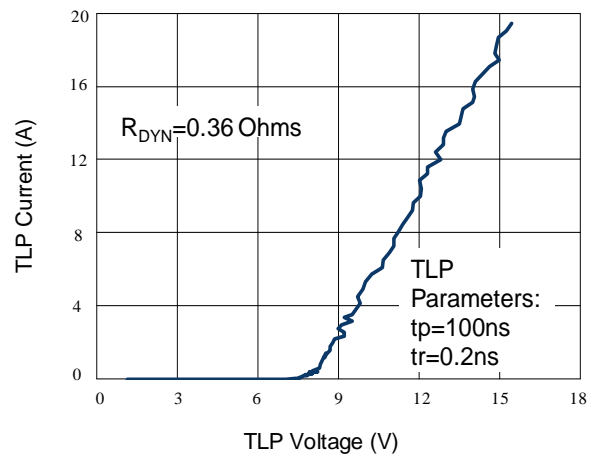
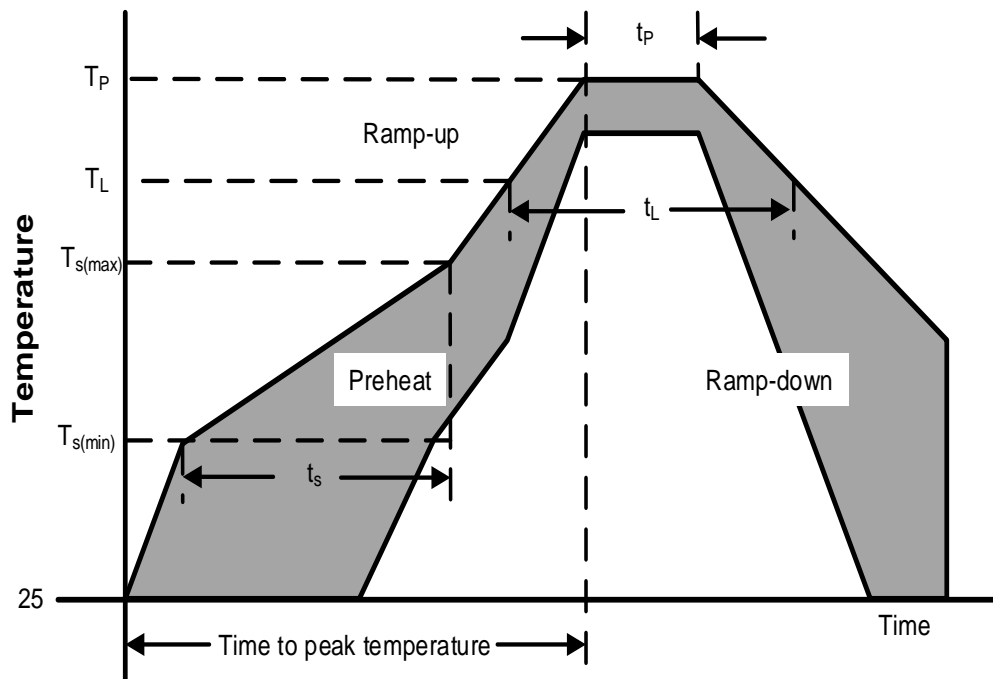


Figure 6: TLP I-V Curve



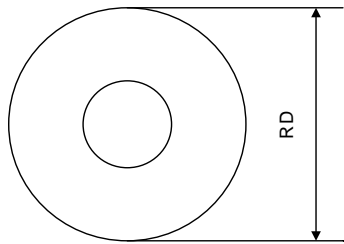
**Soldering Parameters**

Reflow Condition		Pb – Free assembly
Pre Heat	Temperature Min ( $T_{s(min)}$ )	150°C
	Temperature Max ( $T_{s(max)}$ )	200°C
	Time (min to max) ( $t_s$ )	60 – 190 secs
Average ramp up rate (Liquidus Temp) ( $T_L$ ) to peak		5°C/second max
$T_{s(max)}$ to $T_L$ —Ramp-up Rate		5°C/second max
Reflow	Temperature ( $T_L$ ) (Liquidus)	217°C
	Temperature ( $t_L$ )	60 – 150 seconds
Peak Temperature ( $T_P$ )		260+0/-5 °C
Time within actual peak Temperature ( $t_p$ )		20 – 40 seconds
Ramp-down Rate		5°C/second max
Time 25°C to peak Temperature ( $T_P$ )		8 minutes Max.
Do not exceed		280°C

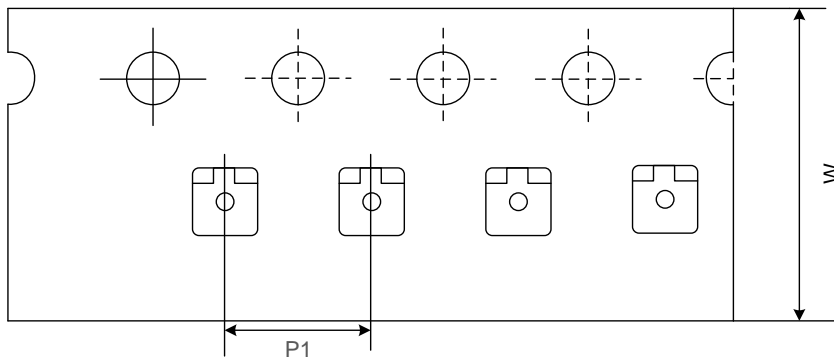


**Tape And Reel Information**

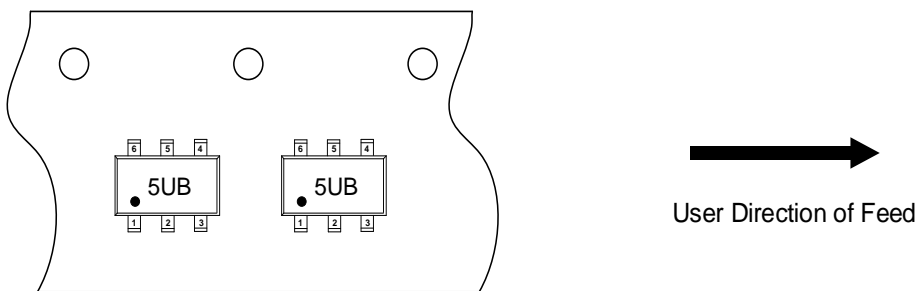
**Reel Dimensions**



**Tape Dimensions**



**Quadrant Assignments For PIN1 Orientation In Tape**



RD	Reel Dimensions	7 inch
W	Overall width of the carrier tape	8 mm
P1	Pitch between successive cavity centers	4mm

Outline Drawing – SOT-23-6L

**PACKAGE OUTLINE**

SOT-23-6L

DIMENSIONS				
DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.035	0.057	0.90	1.45
A1	0.000	0.006	0.00	0.15
A2	0.035	0.051	0.90	1.30
b	0.014	0.020	0.35	0.50
c	0.003	0.008	0.08	0.20
D	0.110	0.119	2.80	3.02
E1	0.060	0.069	1.50	1.75
E	0.102	0.118	2.60	3.00
e	0.037 BSC		0.95 BSC	
e1	0.075 BSC		1.90 BSC	
L	0.014	0.024	0.35	0.60
L1	0.022	0.030	0.55	0.75
θ 1	0°	8°	0°	8°
N	6		6	

DIMENSIONS		
DIM	INCHES	MILLIMETERS
C	0.098	2.50
G	0.055	1.40
P	0.037	0.95
X	0.024	0.60
Y	0.043	1.10
Z	0.141	3.60

**Notes:**

Controlling Dimension: Millimeter.

**Marking Codes**

Part Number	WS05-4R
Marking Code	

**Package Information**

Qty: 3k/Reel

**CONTACT INFORMATION**

No.1001, Shiwan(7) Road, Pudong District, Shanghai, P.R.China.201207

Tel: 86-21-68969993 Fax: 86-21-50757680 Email: [market@way-on.com](mailto:market@way-on.com)

WAYON website: <http://www.way-on.com>

For additional information, please contact your local Sales Representative.

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Specifications are subject to change without notice.  
The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time.  
Users should verify actual device performance in their specific applications.